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**IN THE CLAIMS:**

Please amend claims 1, 3, and 11 without prejudice or disclaimer as shown in the attached sheets.

### REPLACEMENT CLAIMS

Please substitute the following claims for the pending claims with the same number.

1. (Twice Amended) A method of making infrared data communication modules comprising the steps of:
  - forming predetermined conductor patterns on an obverse and a reverse surfaces of a substrate;
  - mounting, on one of the surfaces of the substrate, plural sets of light emitting elements and light receiving elements;
  - resin-molding a non-cut package which encloses the plural sets of light emitting elements and light receiving elements on the substrate; and
  - dividing the non-cut package into a plurality of cut packages each of which encloses a respective set of light emitting element and light receiving element;
  - wherein the mounting step includes arranging the plural sets of light emitting elements and light receiving elements in a matrix on said one surface of the substrate; and
  - wherein the resin-molding step includes forming a plurality of non-cut packages arranged in a matrix.

3. (Twice Amended) The method of making infrared data communication modules according to claim 1, wherein the substrate is elongated in one direction, the substrate being formed with a plurality of slits extending widthwise of the substrate and spaced from each other longitudinally of the substrate, the plural sets of light emitting elements and light receiving elements being mounted on said one surface of the substrate in each of regions defined between the slits.

11. (Amended) An infrared data communication module comprising:  
a substrate having an obverse surface and a reverse surface,  
a wiring pattern formed on the obverse surface of the substrate,  
a set of light emitting element and light receiving element mounted on the obverse surface of the substrate in electrical connection to the wiring pattern,  
a resin package formed on the obverse surface of the substrate for enclosing the set of light emitting element and light receiving element,  
a plurality of terminals formed on the reverse surface of the substrate in electrical connection to the wiring pattern, and  
a dummy pattern formed on the reverse surface of the substrate but electrically separated from the wiring pattern and the terminals, the dummy pattern corresponding in position and in general configuration to the wiring pattern.